

MEG-01-004



November 1, 2003

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Ave
Poughkeepsie, NY 12603

Subject: | Serial No. 09/837,007 04/18/01 |
|
Mou-Shiung Lin
"A STRUCTURE AND MANUFACTURING
METHOD OF A CHIP SCALE PACKAGE"

Grp. Art Unit: 2827 J. MITCHELL

RESPONSE PATENT OFFICE ACTION

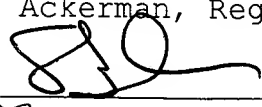
Dear Sir:

In response to the Office Action dated July 1, 2003, please
amend the above-identified application for patent as follows:

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents, P.O.
Box 1450, Alexandria, VA 22313-1450, on November 3, 2003.

Stephen B. Ackerman, Reg. No. 37,761

Signature 

Date 11/3/03

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